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In cooperation with:

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Venue: Hilton Hotel in Dresden

Dresden at the river Elbe
Cover picture: Courtesy of Toppan Photomasks

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Mr. H. Wolf, Photronics MZD GmbH, Dresden, Germany
Dr. S. Wurm, SEMATECH, Albany , NY, USA
Mr. L. Zurbrick, Agilent Technologies, Santa Clara, CA, USA

Please find the members of the **International Steering Committee** of the EMLC on the website: www.emlc2011.com

GMM VDE/VDI-GESELLSCHAFT MIKROELEKTRONIK, MIKROSYSTEM- UND FEINWERKTECHNIK

Call for Papers

The 27th European Mask and Lithography Conference EMLC 2011

January 18 – 19, 2011
Hilton Hotel
Dresden, Germany

www.EMLC2011.com

The VDE/VDI-Society Microelectronics, Micro- and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

27th European Mask and Lithography Conference, EMLC 2011 at the Hilton Hotel in Dresden, Germany January 18 - January 19, 2011

The focus of this two-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.
This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

Conference Schedule:

The conference will start on Tuesday, January 18, 2011, at 09:00 AM with a Keynote Session. The conference will close on Wednesday, January 19, 2011, late afternoon. The Poster Session will be held on Tuesday evening followed by the Conference Banquet Dinner.

Technical Exhibition:

On Tuesday and Wednesday there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the enclosed registration form to the conference chairperson as soon as possible, since exhibition space is limited.

Conference Chairperson and Exhibition Organization:

Dr. Uwe Behringer,
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D-72119 Ammerbuch, Germany
Phone: +49-171-4553196,
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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including (figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2011.com
There you will find a link to myspie.org

Deadline for Abstracts: September 30th 2010

By submitting an abstract you agree to

- Present your work in person at the conference
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **October 15th 2010**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript a.s.a.p.

As to further information concerning the submission procedure, please have a look at our homepage,
www.emlc2011.com

Deadline for Manuscripts: November 30th 2010

All manuscripts will be subject to a critical peer review before they are accepted for publication in the SPIE Digital Library.

Please note: Late submissions may not be published.

Information on the format of the manuscripts and further details is also provided at the conference web site:
www.emlc2011.com

The conference manuscripts will be published by SPIE

Conference Topics:

Presentations are solicited for the following and related topics:

Mask Manufacturing:

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business:

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application:

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies:

- EUV Materials, Tools & Processes
- EUV Mask Infastructure
- NIL
- Direct Write / Maskless Technologies

Mask and Lithography Equipment